

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: J. H. Magerlein et al.
Title: High Density Area Array Solder Microjoining Interconnect Structure
and Fabrication Method
Filed: Herewith
Serial No.: Not yet assigned
Examiner: Not yet assigned
Art Unit: Not yet assigned
Docket No.: YOR920010216US2

Prior Application:

Serial No: 10/052620
Filed: January 18, 2002
Docket No.: YOR920010216US1
Examiner: David Nhu
Art Unit: 2828

Customer No.22032

Mail Stop Patent Application

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PRELIMINARY AMENDMENT

In advance of substantive examination, please amend the above-identified
patent application as follows: